
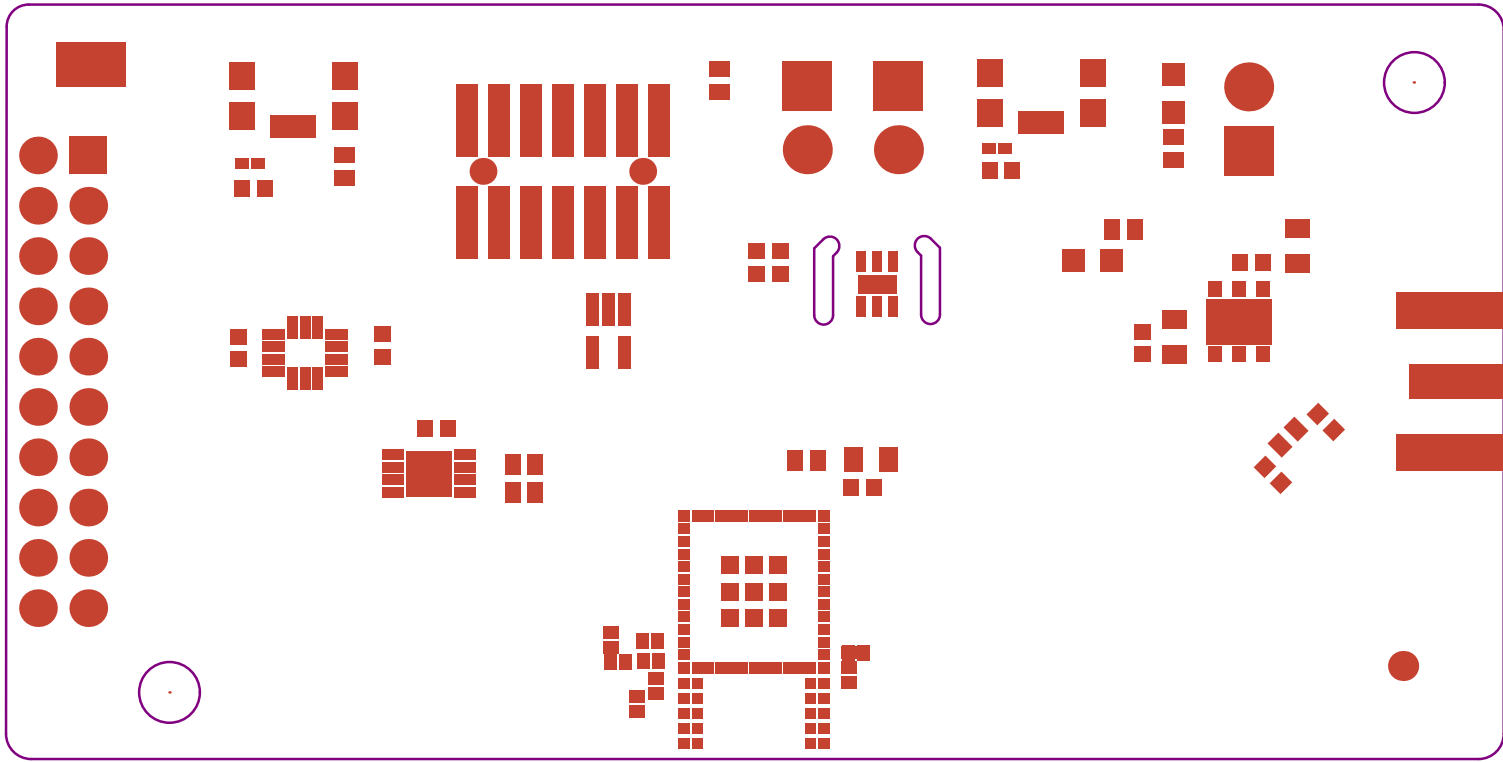

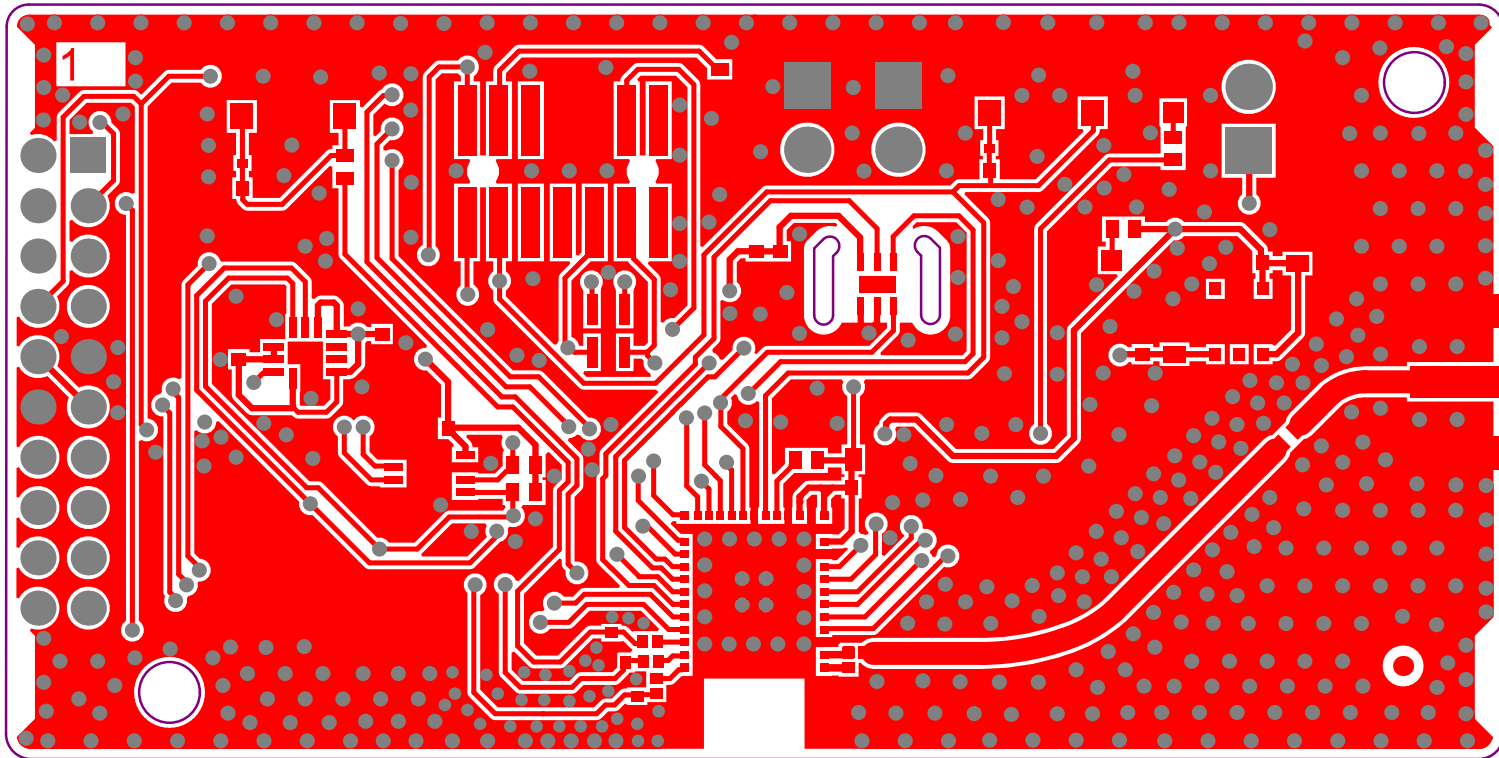



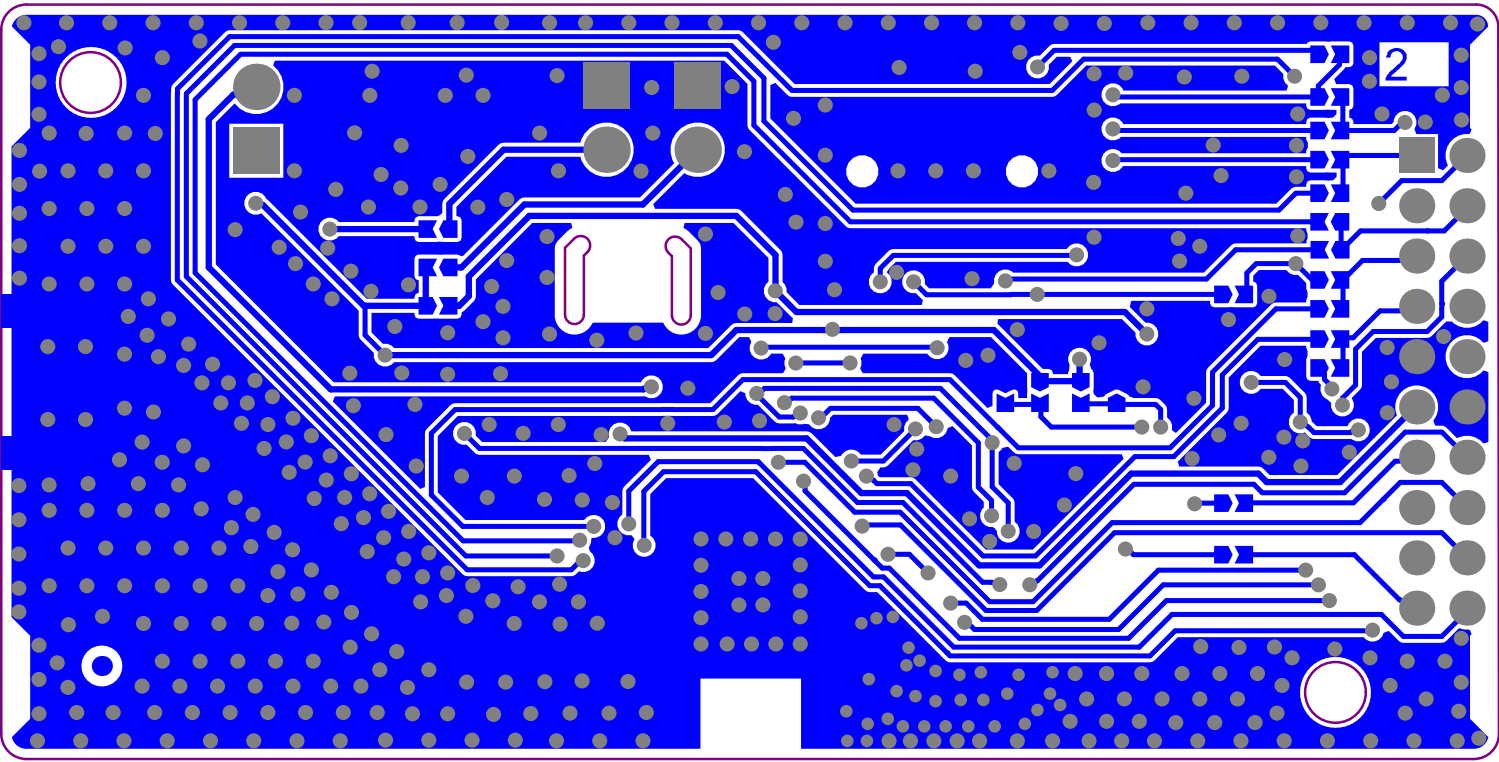
Project: STM32WB1M STMod+ expansion board		
Layer: Top Overlay	Gerber: .GTO	
Variant: [No Variations]	Ref: MB1868	
Date: 29-JUN-2023	Rev: E	




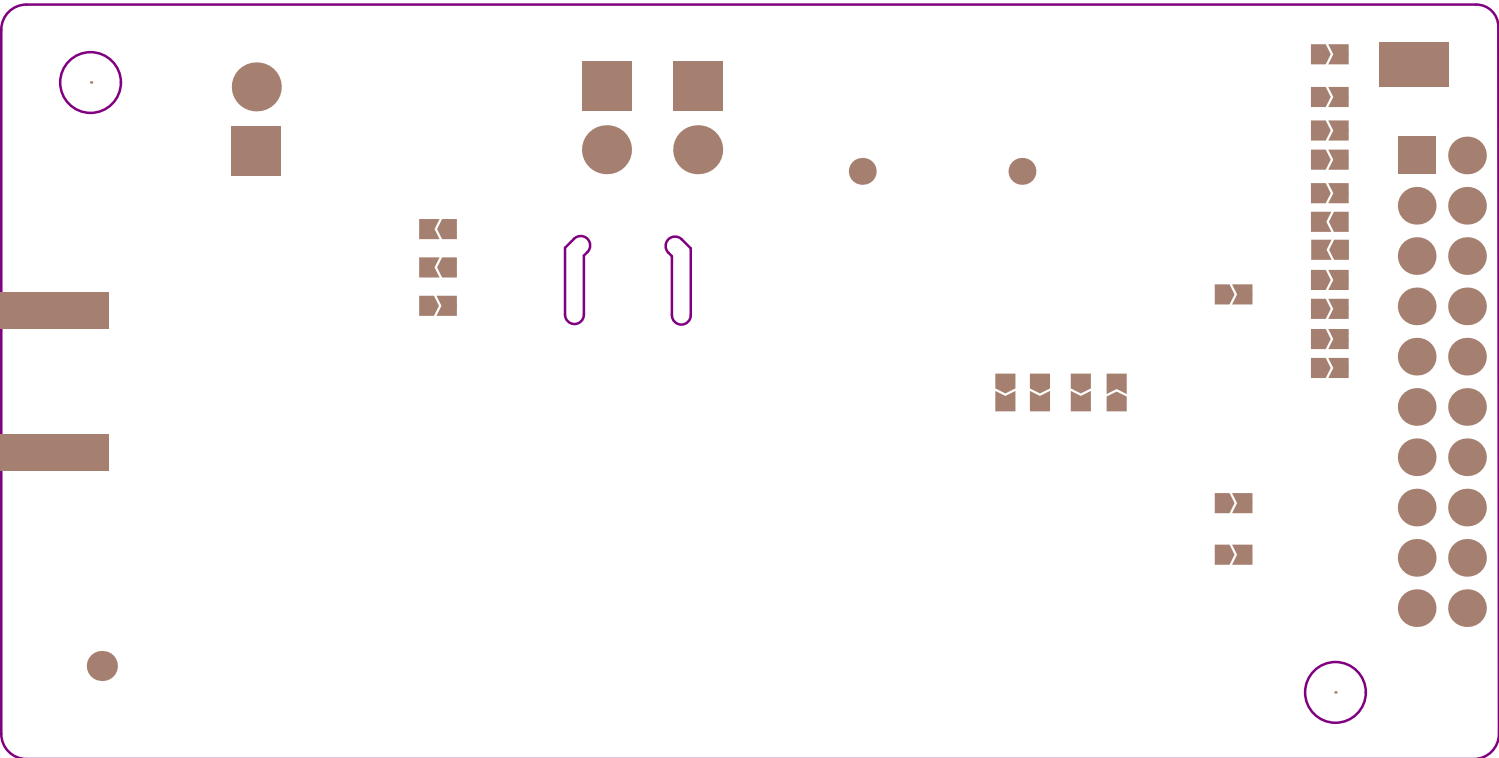
Project: STM32WB1M STMod+ expansion board		
Layer: Top Solder	Gerber: .GTS	
Variant: [No Variations]	Ref: MB1868	
Date: 29-JUN-2023	Rev: E	




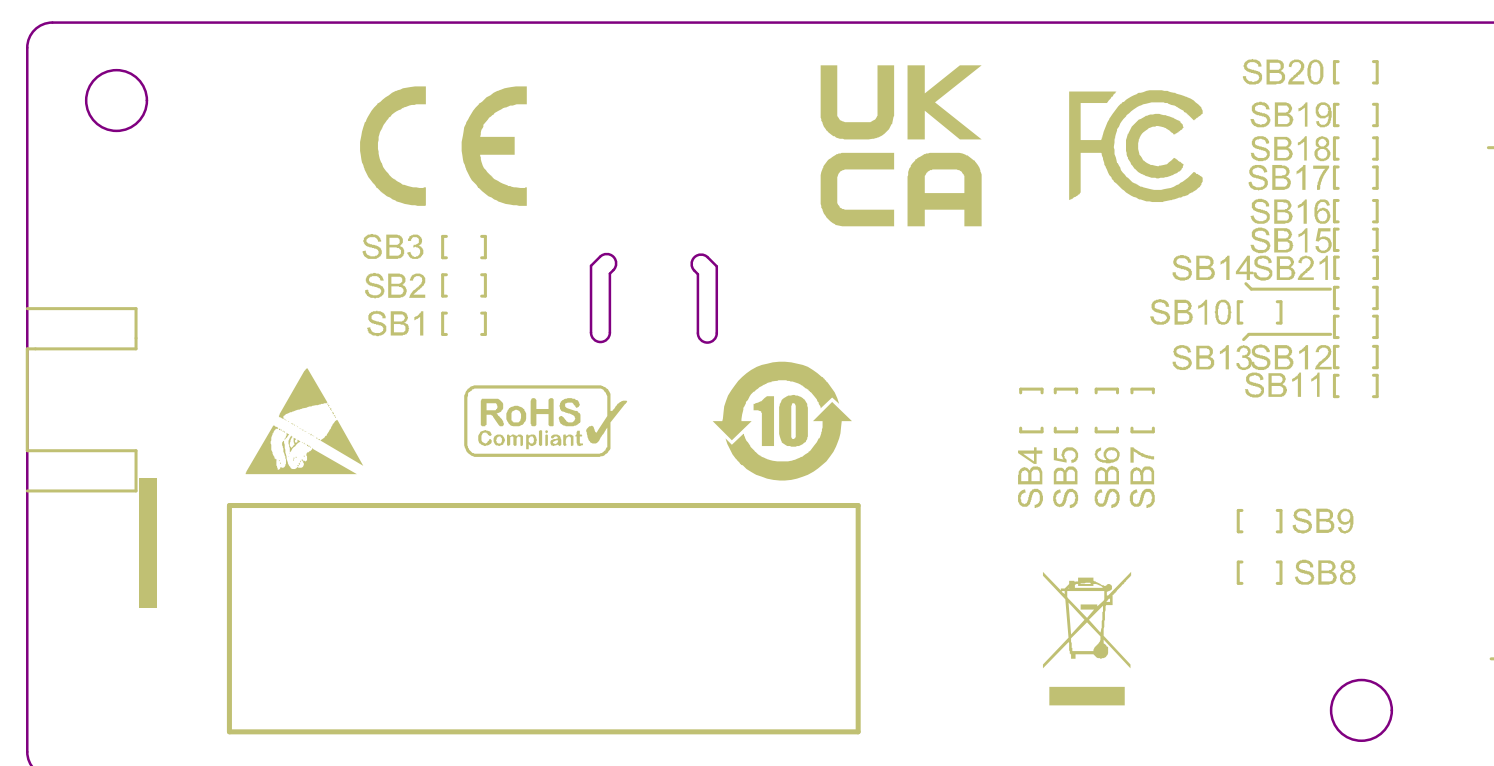
Project: STM32WB1M STMod+ expansion board		
Layer: Top Layer	Gerber: .GTL	
Variant: [No Variations]	Ref: MB1868	
Date: 29-JUN-2023	Rev: E	




Project: STM32WB1M STMod+ expansion board		
Layer: Bottom Layer	Gerber: .GBL	
Variant: [No Variations]	Ref: MB1868	
Date: 29-JUN-2023	Rev: E	



Project: STM32WB1M STMod+ expansion board		
Layer: Bottom Solder	Gerber: .GBS	
Variant: [No Variations]	Ref: MB1868	
Date: 29-JUN-2023	Rev: E	



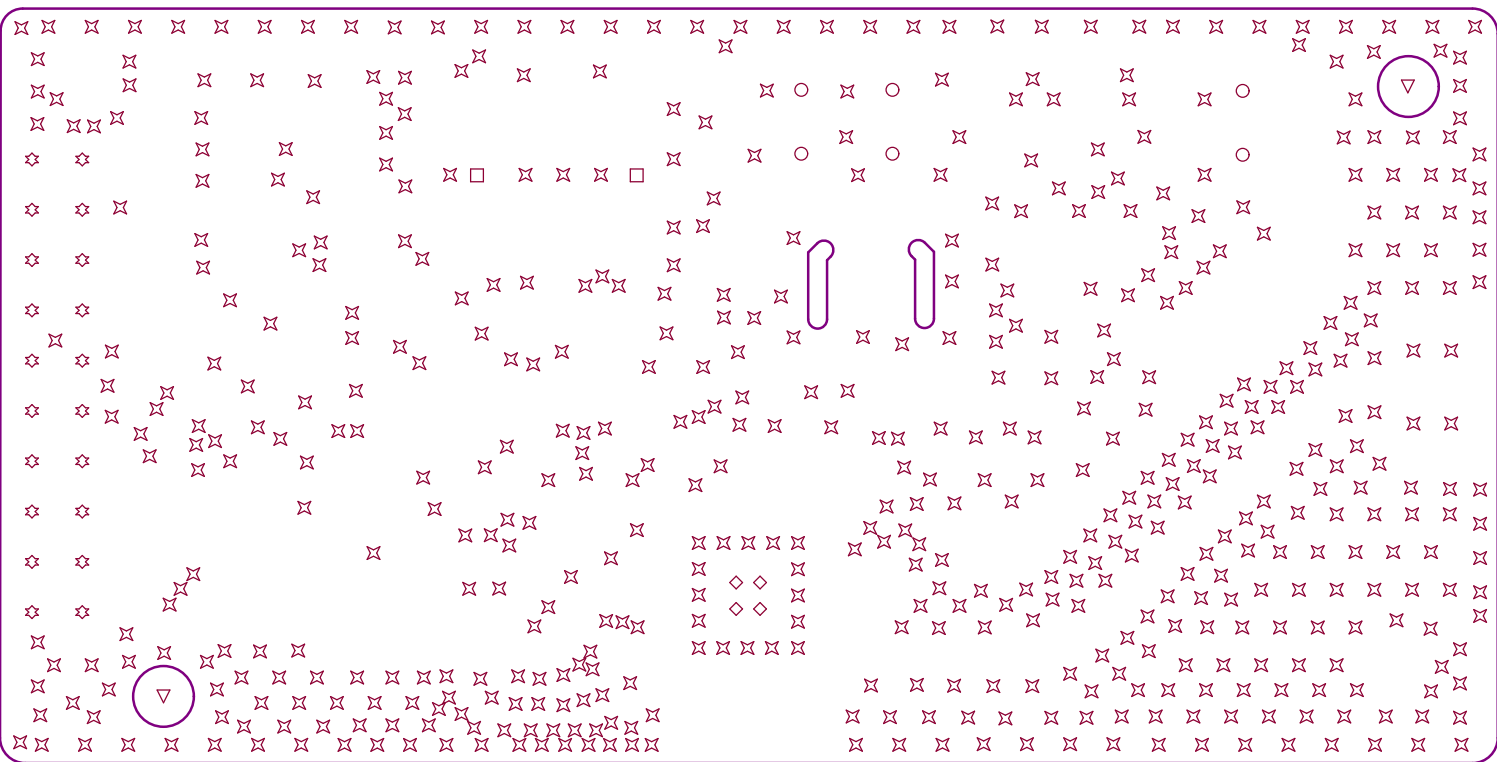
Project: STM32WB1M STMod+ expansion board		
Layer: Bottom Overlay	Gerber: .GBO	
Variant: [No Variations]	Ref: MB1868	
Date: 29-JUN-2023	Rev: E	

THE COMPONENTS WITH PLATED THROUGH HOLE (PTH) MAY BE WELDED (CABLED) IN "PIN-IN-PASTE" MODE (IF NECESSARY)
""TOP PASTE""


MINIMUM PARAMETERS	PCB : TYPE 2
DEFAULT TRACKS : 0.20mm GAPS : 0.15mm	ASPECT-RATIO, AXE Z : < 6:1 LEVEL "A"







PCB SPECIFICATIONS :

A. MATERIAL :	FR-4	<input type="checkbox"/> TG-170	<input type="checkbox"/> TG-150	<input checked="" type="checkbox"/> TG-140
B. MATERIAL FAMILY :	N/A			
C. SOLDERMASK COLOR :	<input type="checkbox"/> GREEN	<input type="checkbox"/> WHITE	<input type="checkbox"/> RED	<input checked="" type="checkbox"/> Blue ink PANTONE 2955
D. SILKSCREEN COLOR :	<input checked="" type="checkbox"/> WHITE	<input type="checkbox"/> YELLOW	<input type="checkbox"/> BLACK	<input type="checkbox"/> Blue ink PANTONE 2955
E. SURFACE FINISH :	<input checked="" type="checkbox"/> ENIG	<input type="checkbox"/> IMMERSION SILVER	<input type="checkbox"/> IMMERSION TIN	
	<input type="checkbox"/> HASL	<input type="checkbox"/> HASL (PB-FREE)	<input type="checkbox"/> GOLDEN FINGER	
<input type="checkbox"/> IMPEDANCE CONTROL :	<input type="checkbox"/> NO	<input type="checkbox"/> YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)		
G. THROUGH VIA :	PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.			
	PLUG MATERIAL : <input checked="" type="checkbox"/> SOLDERMASK <input type="checkbox"/> NON-CONDUCTIVE EPOXY.			
<input type="checkbox"/> STACK-UP :	SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.			



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.020mm	4.2	
1	Top Layer		0.018mm		
	Dielectric 2	FR-4	1.464mm	4.2	
2	Bottom Layer		0.018mm		
	Bottom Solder	Solder Resist	0.020mm	4.2	
	Bottom Overlay				

Project: STM32WB1M STMod+ expansion board		
Layer: Drill Drawing	Gerber: .DRL	
Variant: [No Variations]	Ref: MB1868	
Date: 29-JUN-2023	Rev: E	

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape
	2	0.970mm (38.19mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded
	2	2.500mm (98.43mil)	NPTH	Slot	Top Layer - Bottom Layer	Pad	Rounded
	4	0.300mm (11.81mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded
	6	1.000mm (39.37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded
	20	0.900mm (35.43mil)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)
	550	0.300mm (11.81mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded
	584 Total						

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout